What Is Claimed Is:

1. A printed circuit board assembly, including:

a first board containing a first circuit; and

a second board smaller than the first board and disposed on the first board, wherein the second board contains a second circuit electrically connected to the first circuit.

2. A printed circuit board as claimed in claim 1, wherein the second board defines at least one cavity with the first board.

3. A printed circuit board assembly, including:

a first circuit board including a first surface and a second surface opposite each other;

a second circuit board smaller than the first circuit board, disposed on the first surface of the first circuit board and electrically connected to the first circuit board; and

a third circuit board smaller than the first circuit board, disposed on the second surface of the first circuit board and electrically connected to the first circuit board.

4. A printed circuit board as claimed in claim 3, wherein the second circuit board is as large as the third circuit board.

5. A printed circuit board as claimed in claim 3, wherein the second circuit board defines at least one cavity with the first circuit board.

6. A printed circuit board as claimed in claim 3, wherein the third circuit board defines at least one cavity with the first circuit board.

7. An electrical combination comprising:

a multi-layer printed circuit board having different regions with different heights; and

a plurality of electronic components mounted on the printed circuit board, wherein the electronic components have different thickness, wherein the electronic component with the more thickness is mounted on the region of the printed circuit board with the less height.

8. The electrical combination as claimed in claim 7 further comprising a cover covering the printed circuit board and the electronic components without interference with the electronic components.

9. The electrical combination as claimed in claim 8, wherein the cover comprises at least a protrusion extending toward the printed circuit board.

10. The electrical combination as claimed in claim 9, wherein the electronic component with the less thickness is located below the at least one protrusion.

11. The electrical combination as claimed in claim 7, wherein the different regions of the printed circuit board with different heights are arranged in a stepped form.